

S/N 10/033,322

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Favorable reconsideration of this application is requested in view of the above amendments and the following remarks. Claims 1-12 and 23-44 are pending in the application. The revisions to claim 1 and new claims 43 and 44 are supported in the figures.

Claims 1-3, 5, 25, 26 and 37-42 have been rejected as obvious over Nakatani in view of Hirai. Applicants respectfully traverse this rejection.

The rejection relies on Hirai as teaching an electric insulating layer 70 formed on at least one surface of a core layer 4, with the core layer and the electric insulating layer being formed of different electric insulating materials. This refers to Figure 7 and column 7, lines 24-40 of the reference. See page 4 of the Office Action.

However, the disclosure of Hirai is not suitable for combination with Nakatani to meet the requirements of claim 1. Claim 1 requires a wiring pattern on the electric insulating layer as well as a wiring pattern on the core layer. In contrast, Hirai is directed to an IC module and IC card. Element 70 of Hirai is a coversheet for the card body. Nothing in Hirai or Nakatani would suggest any reason for providing a wiring pattern on the cover sheet. Furthermore, there is no reason for one of ordinary skill to consider providing electrical connection between such a wiring pattern formed on the coversheet and a wiring pattern formed on the core layer as required by claim 1. The IC card of Hirai is completely different from a component built-in module according to the present invention, and therefore Hirai would not suggest modifications of the Nakatani disclosure to one of ordinary skill in the art.

Claims 2 and 3 are further removed from the references. Claim 2 requires that "the thermosetting resin comprises a plurality of thermosetting resins having different glass transition temperatures". The thermosetting resin is defined earlier in claim 2 as being a component of the electric insulating material of the core layer. Nothing in the references suggests the use of plural thermosetting resins in the core layer. Claim 3 further specifies this particular glass transition

S/N 10/033,322

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temperature ranges for the thermosetting resins used for the electric insulating material of the core layer.

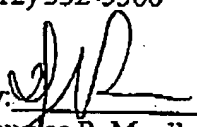
Dependent claims 43 and 44 are further removed from the references as well. The requirement in claim 43 of electrical connection between the wiring pattern of the core layer and the active and/or passive component with the wiring pattern on the electric insulating layer is even further removed from the IC card of Hirai, as is the requirement in claim 44 of multiple electric insulating layers with wiring patterns.

In view of the above, favorable reconsideration in the form of a Notice of Allowance is requested.

Respectfully submitted,

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